

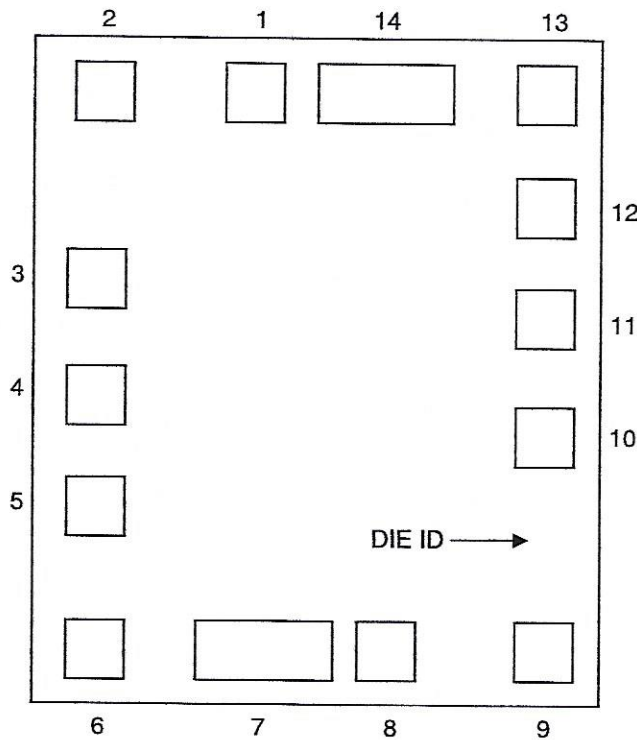


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



PAD	FUNCTION
1	1 \bar{R}
2	1D
3	1CP
4	1 \bar{S}
5	1Q
6	1 \bar{Q}
7	GND
8	2 \bar{Q}
9	2Q
10	2 \bar{S}
11	2CP
12	2D
13	2 \bar{R}
14	V _{cc}

Top Material: Aluminum
Backside Material: Silicon
Bond Pad Size: .004" X .004" min.
Backside Potential: V_{cc} or Float
Mask Ref: 0233

APPROVED BY: DK

DIE SIZE .043 x .052"

DATE: 9/16/16

MFG: Zytrex Semi.

THICKNESS .025"

P/N: 54HCT74